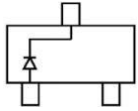
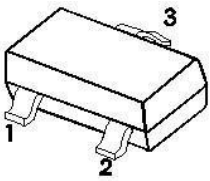


SOT-23 贴片塑封二极管

SOT-23 Plastic-Encapsulate Diode

SOT-23



Marking: D3E

特征 Features

- 低电流整流。Low current rectification
- 反向漏电流小。Low IR
- 高可靠性。High reliability

机械数据 Mechanical Data

- 封装: SOT-23 封装 SOT-23 Small Outline Plastic Package
- 环氧树脂 UL 易燃等级 Epoxy UL: 94V-0
- 安装位置: 任意 Mounting Position: Any

极限值和温度特性(TA = 25℃ 除非另有规定)

Maximum Ratings & Thermal Characteristics (Ratings at 25℃ ambient temperature unless otherwise specified.)

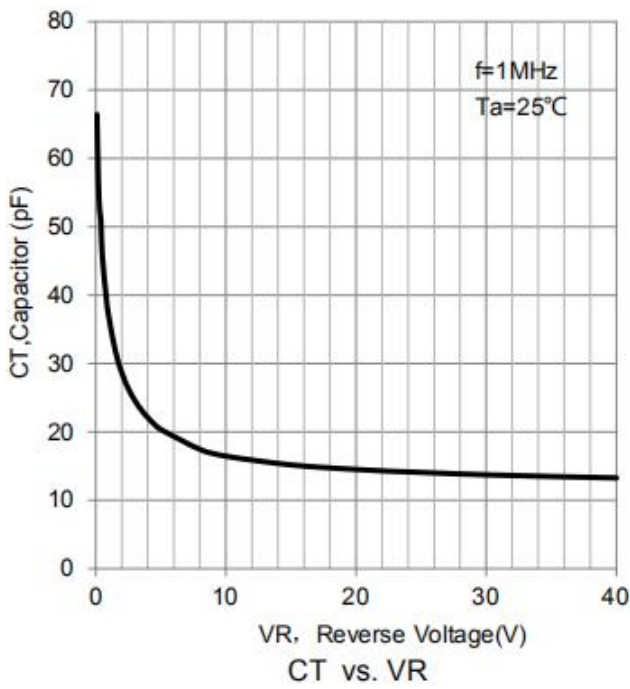
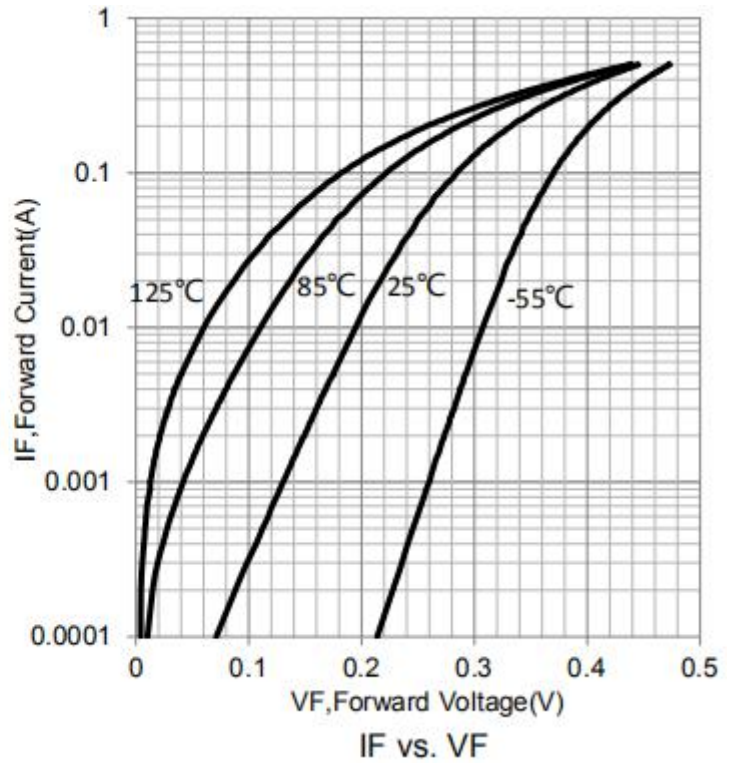
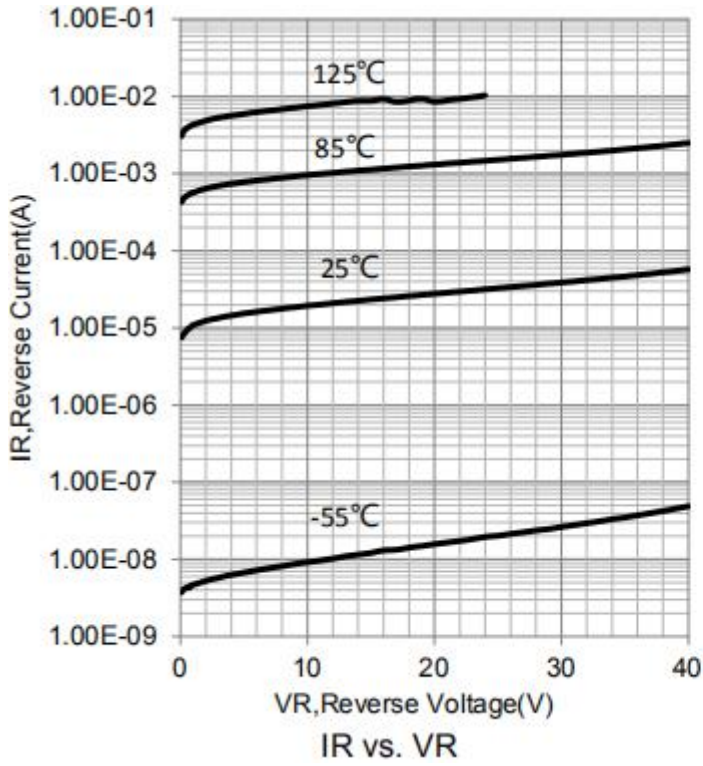
参数 Parameters	符号 Symbol	数值 Value	单位 Unit
反向峰值电压 Peak Repetitive Reverse Voltage	VRM	40	V
反向电压 Reverse Voltage	VR	20	V
平均正向整流电流 Average Rectified Forward Current	IO	500	mA
峰值正向浪涌电流 Forward Current Surge Peak	IFSM	3	A
结温 Junction Temperature	Tj	125	℃
存储温度 Storage temperature range	TSTG	-40-+125	℃

电特性 (TA = 25℃ 除非另有规定)

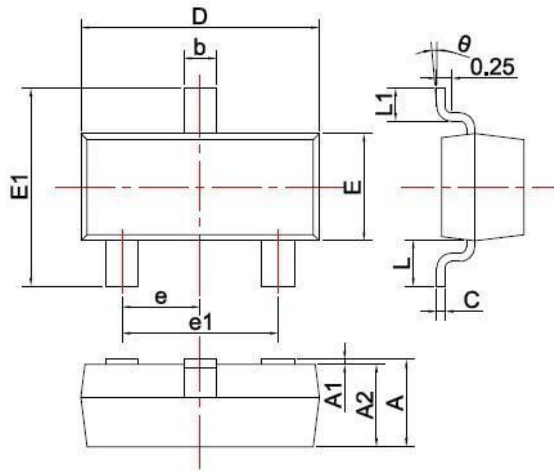
Electrical Characteristics (Ratings at 25℃ ambient temperature unless otherwise specified.)

符号 Symbols	参数 Parameter	测试条件 Test Condition	界限 Limits			单位 Unit
			Min	Typ	Max	
VF	正向电压 Forward Voltage	IF=500mA	--	--	0.5	V
		IF=10mA	--	--	0.3	
IR	反向漏电流 Reverse Leakage Current	VR=10V	--	--	30	uA
CT	结电容 Capacitance Between Terminal	VR=10V, f=1MHZ	--	16	--	pF

Typical Characteristics



SOT-23 PACKAGE OUTLINE Plastic surface mounted package



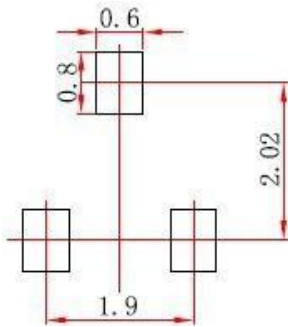
SYMBOL	DIMENSIONS	
	MIN.	MAX.
A	0.900	1.150
A1	0.000	0.100
A2	0.900	1.050
b	0.300	0.500
c	0.080	0.150
D	2.800	3.000
E	1.200	1.400
E1	2.250	2.550
e	0.950TYP	
e1	1.800	2.000
L	0.550REF	
L1	0.300	0.500
θ	0°	8°

Unit: mm

焊盘设计参考

Precautions: PCB Design

Recommended land dimensions for SOT-23 diode. Electrode patterns for PCBs



Note:

1. Controlling dimension: In millimeters.
2. General tolerance: ± 0.05mm.
3. The pad layout is for reference purposes only.